Panasonic

Junction FETs DSK5J01×0L

DSK5J01×0L Silicon N-channel Junciton FET

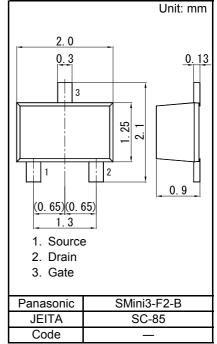
For low frequency amplificaton / For pyroelctric sensor DSK2J01 in SMini3 type package

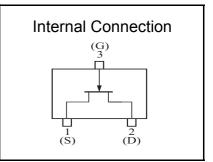
Features

- High gate-drain Voltage(Source open)VGDO
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: B6

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)





■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Gate-drain voltage (Source short)	VGDS	-55	V
Drain current	ID	30	mA
Gate current	IG	10	mA
Power dissipation	PD	150	mW
Channel temperature	Tch	150	С°
Operating ambient temperature	Topr	-40 to +85	С°
Storage temperature	Tstg	-55 to +150	°C

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Gate-drain voltage (Source short)	VGDS	IG = -100 μA, VDS = 0	-55			V		
Drain current *1	IDSS	VDS = 10 V , VGS = 0	1.0		12.0	mA		
Gate-source cutoff current	IGSS	VGS = -30 V, VDS = 0			-10	nA		
Gate-source cutoff voltage	VGSC	VDS = 10 V, ID = 10 µA			-5	V		
Forward transfer admittance	Yfs	VDS = 10 V, ID = 5 mA, f =1 kHz	2.5	7.5		mS		
Small-signal short-circuit input capacitance	Ciss	VDS = 10 V, VGS = 0, f = 1 MHz		6.0		pF		
Small-signal reverse transfer capacitance	Crss	VD3 = 10 V, VG3 = 0,1 = 1 WHZ		2.5		pF		

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

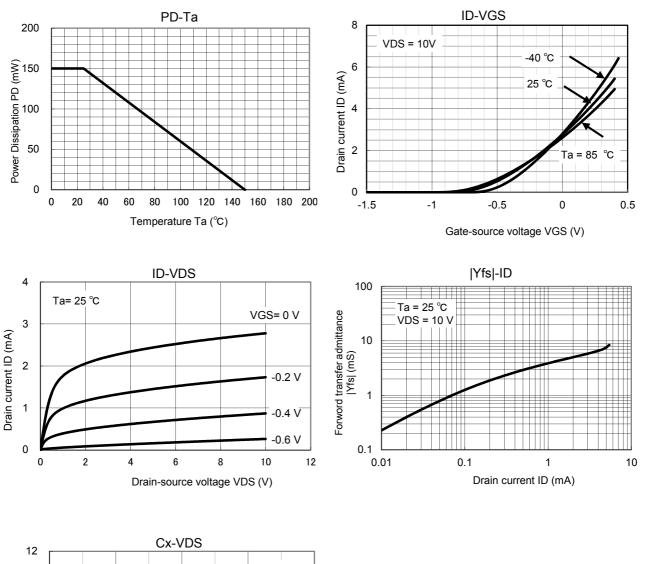
*1 Rank classification

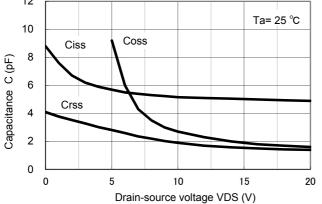
Code	Р		Q		R				
Rank		Р		Q		R			
IDSS (mA)	1.0	to	3.0	2.0	to	6.5	5.0	to 12	.0
Marking symbol	B6P		B6Q		B6R				



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Technical Data (reference)



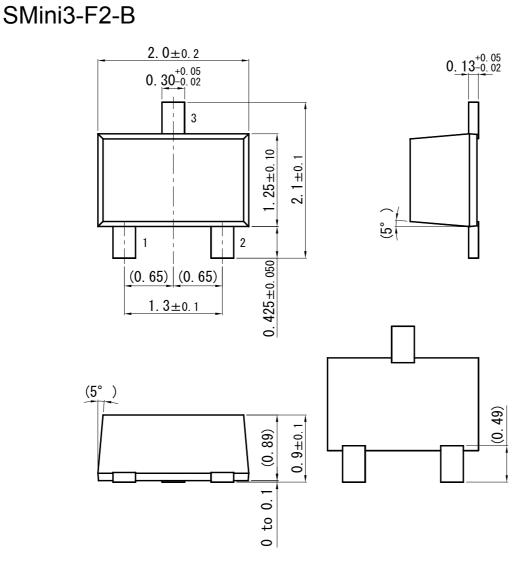


Established : 2010-10-26 Revised : 2014-03-25

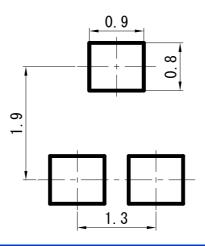


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Unit: mm



Land Pattern (Reference) (Unit: mm)



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